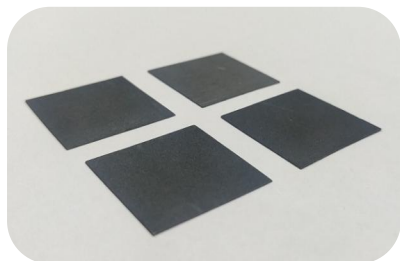




## DATA SHEET



-Product picture-

### FEATURES:

- Soft surface, good compressibility
- Low thermal resistance
- Application under low pressure
- Good thermal stability

### APPLICATIONS:

- Base station
- Chip
- Large server
- Data processing center

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

**STORAGE CONDITIONS:** Storage in the darkness

**STORAGE TEMPERATURE:**  $\leq 30^{\circ}\text{C}$

**STORAGE HUMIDITY:**  $\leq 70\%$

### SHELF LIFE:

Under storage conditions: 2 year

Non storage conditions: 6 months.

HFC HCF-03E is an ultra-thin new carbon fiber thermal pad with ultra-low thermal resistance. The thermal pad mainly uses carbon fiber as a highly thermally conductive filler, using advanced preparation technology to make the carbon fiber vertically arranged in the polymer matrix to form a good thermal conduction path in the vertical direction, greatly enhance the heat transfer efficiency, particularly applicable to base station, chip, etc high heat flux equipment. In addition, the ultra-thin carbon fiber thermal pad has high flexibility and ultra-low thermal resistance, which can be used as thermal grease replaced material.

### PROPERTIES

Items	Parameter	Test Method
Color	Gray black	Visual
Standard Size (mm)	120*120	ASTM D 5947
Thickness (mm)	0.3~3( $\pm 10\%$ )	ASTM D 374
Hardness (Shore 00)	65( $\pm 10$ )	ASTM D 2240
Density (g/cc)	1.85( $\pm 0.2$ )	ASTM D 792
Rebound Rate (%)	> 30	ASTM D 575
Rate Of Oil Yield (%)	< 3	HFC
Operating Temperature ( $^{\circ}\text{C}$ )	-40~125	IEC 60068-2-14

### THERMAL CHARACTERISTIC

Thermal Resistance ( $^{\circ}\text{C}\cdot\text{in}^2/\text{W}$ )	$\leq 0.04_{(@40\text{psi}/0.3\text{mm})}$	ASTM D 5470
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